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MTP20N15E

Power MOSFET 20 Amps, 150 Volts N-Channel TO-220

This Power MOSFET is designed to withstand high energy in the avalanche and commutation modes. The energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for low voltage, high speed switching applications in power converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional safety margin against unexpected voltage transients.

- Avalanche Energy Specified
- Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
- Diode is Characterized for Use in Bridge Circuits
- I_{DSS} and V_{DS(on)} Specified at Elevated Temperature
- This is a Pb-Free Device*

MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

() ()						
Rating	Symbol	Value	Unit			
Drain-Source Voltage	V _{DSS}	150	Vdc			
Drain–Gate Voltage (R_{GS} = 1.0 M Ω)	V _{DGR}	150	Vdc			
Gate–Source Voltage – Continuous – Non–Repetitive (t _p ≤ 10 ms)	V _{GS} V _{GSM}	± 20 ± 32	Vdc			
Drain – Continuous – Continuous @ 100°C – Single Pulse (t _p ≤ 10 μs)	I _D I _D I _{DM}	20 12 60	Adc			
Total Power Dissipation Derate above 25°C	P _D	112 0.9	Watts W/°C			
Operating and Storage Temperature Range	T _J , T _{stg}	–55 to 150	°C			
Single Drain-to-Source Avalanche Energy – Starting $T_J = 25^{\circ}C$ ($V_{DD} = 120 \text{ Vdc}, V_{GS} = 10 \text{ Vdc},$ $I_L = 20 \text{ Apk}, L = 0.3 \text{ mH}$)	E _{AS}	60	mJ			
Thermal Resistance – Junction to Case – Junction to Ambient	R _{θJC} R _{θJA}	1.1 62.5	°C/W			
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	TL	260	°C			

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

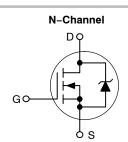
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



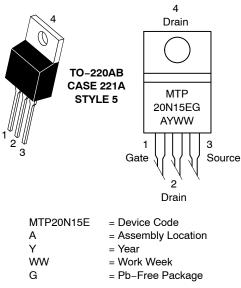
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20 AMPERES 150 VOLTS R_{DS(on)} = 130 mΩ







ORDERING INFORMATION

Device	Package	Shipping
MTP20N15EG	TO-220AB (Pb-Free)	50 Units/Rail

Downloaded from Arrow.com.

MTP20N15E

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Ch	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						
Drain–Source Breakdown Voltage (V _{GS} = 0 Vdc, I _D = 0.25 mAdc) Temperature Coefficient (Positive)			150 -	_ TBD		Vdc mV/°C
Zero Gate Voltage Collector Current ($V_{DS} = 150 \text{ Vdc}, V_{GS} = 0 \text{ Vdc}$) ($V_{DS} = 150 \text{ Vdc}, V_{GS} = 0 \text{ Vdc}, T_J = 125^{\circ}\text{C}$)					10 100	μAdc
Gate-Body Leakage Current (V _G	I _{GSS(f)} I _{GSS(r)}			100 100	nAdc	
ON CHARACTERISTICS (Note 1.)						
Gate Threshold Voltage (V _{DS} = V _{GS} , I _D = 0.25 mAdc) Temperature Coefficient (Negative	V _{GS(th)}	2.0	_ TBD	4.0 _	Vdc mV/°C	
Static Drain-Source On-Resistar	nce (V _{GS} = 10 Vdc, I _D = 10 Adc)	R _{DS(on)}	-	0.12	0.13	Ohm
$\begin{array}{l} \text{Drain-Source On-Voltage (V_{GS} = } \\ (I_D = 20 \text{ Adc}) \\ (I_D = 10 \text{ Adc}, \text{ T}_J = 125^\circ\text{C}) \end{array}$	V _{DS(on)}			2.8 2.6	Vdc	
Forward Transconductance (V _{DS}	9 _{FS}	8.0	11	-	mhos	
DYNAMIC CHARACTERISTICS			1		1	
Input Capacitance		C _{iss}	-	1133	1627	pF
Output Capacitance	(V _{DS} = 25 Vdc, V _{GS} = 0 Vdc, f = 1.0 MHz)	C _{oss}	-	332	474	
Transfer Capacitance		C _{rss}	-	105	174	1
SWITCHING CHARACTERISTICS	(Note 2.)					
Turn-On Delay Time		t _{d(on)}	-	11	25	ns
Rise Time	(V _{DD} = 75 Vdc, I _D = 20 Adc, V _{GS} = 10 Vdc,	t _r	-	77	153	
Turn-Off Delay Time	$R_{\rm G} = 9.1 \ \Omega$	t _{d(off)}	-	33	67	
Fall Time		t _f	-	49	97	
Gate Charge		QT	-	39.1	55.9	nC
	(V _{DS} = 120 Vdc, I _D = 20 Adc,	Q ₁	-	7.5	-	
	V _{GS} = 10 Vdc)	Q ₂	-	22	-	
		Q ₃	-	17	-	
SOURCE-DRAIN DIODE CHARA	CTERISTICS					
Forward On-Voltage (Note 1.)	$(I_{S} = 20 \text{ Adc}, V_{GS} = 0 \text{ Vdc})$ $(I_{S} = 20 \text{ Adc}, V_{GS} = 0 \text{ Vdc}, T_{J} = 125^{\circ}\text{C})$	V_{SD}			1.5 -	Vdc
Reverse Recovery Time		t _{rr}	_	160	_	ns
,		t _a	_	123	-	1
	(I _S = 20 Adc, V _{GS} = 0 Vdc, dI _S /dt = 100 A/μs)	t _b	_	36.5	_	1
	$uis/ui = 100 A/\mu s$	~				

1. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

Reverse Recovery Stored

Charge

2. Switching characteristics are independent of operating junction temperature.

 $\mathsf{Q}_{\mathsf{R}\mathsf{R}}$

μC

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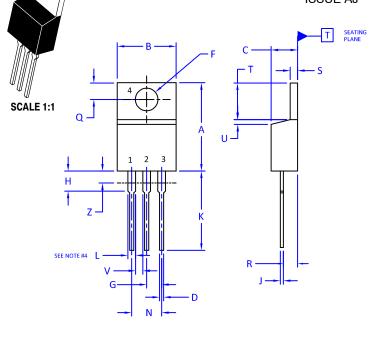
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DATE 05 NOV 2019



TO-220 CASE 221A-09 ISSUE AJ



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 2009.

2. CONTROLLING DIMENSION: INCHES

3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

4. MAX WIDTH FOR F102 DEVICE = 1.35MM

	INCHES		MILLIMETERS	
DIM	MIN.	MAX.	MIN.	MAX.
А	0.570	0.620	14.48	15.75
В	0.380	0.415	9.66	10.53
С	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.60	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
К	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
Ν	0.190	0.210	4.83 5.3	
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.41
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

STYLE 1: PIN 1. 2. 3. 4.	COLLECTOR EMITTER	STYLE 2: PIN 1. 2. 3. 4.	EMITTER COLLECTOR	2. 3.	CATHODE ANODE GATE ANODE	STYLE 4: PIN 1. 2. 3. 4.	MAIN TERMINAL 1 MAIN TERMINAL 2 GATE MAIN TERMINAL 2
STYLE 5: PIN 1. 2. 3. 4.	DRAIN SOURCE	2. 3.	ANODE CATHODE ANODE CATHODE	2. 3.	CATHODE ANODE CATHODE ANODE	2. 3.	CATHODE ANODE EXTERNAL TRIP/DELAY ANODE
STYLE 9: PIN 1. 2. 3. 4.	COLLECTOR EMITTER	STYLE 10: PIN 1. 2. 3. 4.	GATE SOURCE DRAIN		DRAIN SOURCE GATE	STYLE 12 PIN 1. 2. 3. 4.	MAIN TERMINAL 1 MAIN TERMINAL 2 GATE NOT CONNECTED

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DESCRIPTION:	TO-220		PAGE 1 OF 1			
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